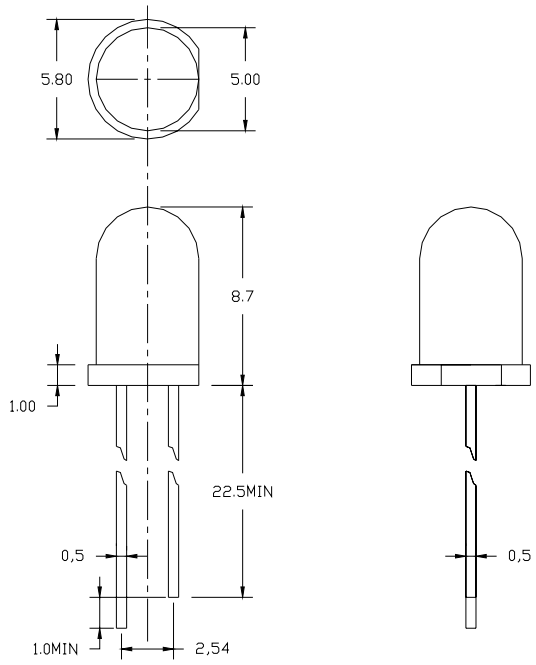
■ Features:

1. Low power consumption
2. High efficiency
3. Reliable and rugged
4. Chip Material: InGaN
5. Lens Color: Water Transparent
6. Source Color: White

■ Outline Dimensions:



Note：

1. All dimensions are in millimeters (inches)
2. Tolerance is ±0.25mm (.010”) unless otherwise noted
3. Protruded resin under flange is 1.0mm (.04”) max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notices.

■ Absolute Maximum Ratings at Ta=25℃:

Parameter	Maximum	Unit
Power Dissipation	120	mW
Peak Forward Current (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
Continuous Forward Current	30	mA
Derating Linear From 50℃	0.5	mA/℃
Reverse Voltage	5	V
Operating temperature range	-20℃ to + 80℃	
Storage Temperature Range	-30℃ to + 100℃	
Lead Soldering Temperature [1.6mm(0.63”) from body]	260℃ for 3 Seconds	

■ Electrical/Optical Characteristics at Ta=25℃:

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I_v	I_F=20mA	5000	6000	7000	mcd
Viewing Angle	2θ1/2	I_F=20mA	40		50	deg
Forward Voltage	V_F	I_F=20mA	3.0		3.2	V
Reverse Current	I_R	V_R=5V			100	uA
Color Rendering	Spm	X	0.240		0.360	
Index Calculation	Spm	Y	0.240		0.360	

■ Typical Electrical/Optical Characteristics Curve: (25℃ Ambient Temperature Unless Otherwise Noted)

Fig1. Relative Intensity vs. Wavelength

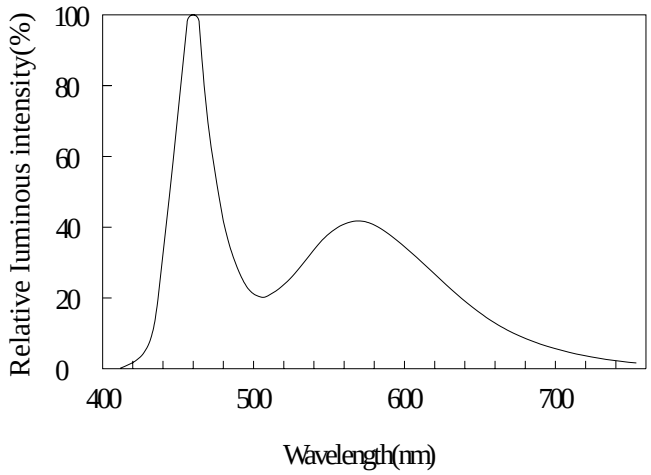


Fig2. Forward Current vs. Forward Voltage

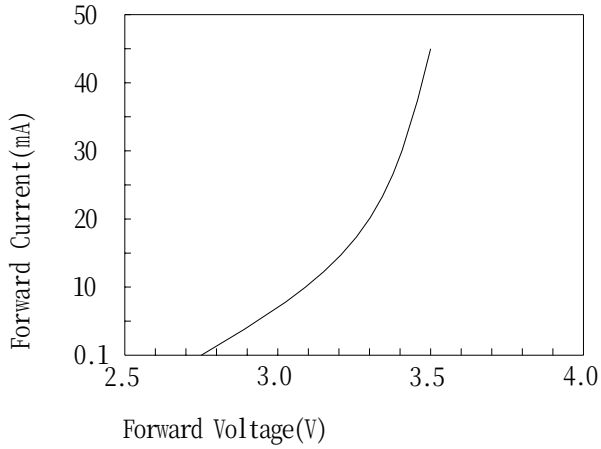


Fig3. Relative Intensity vs. Forward Current

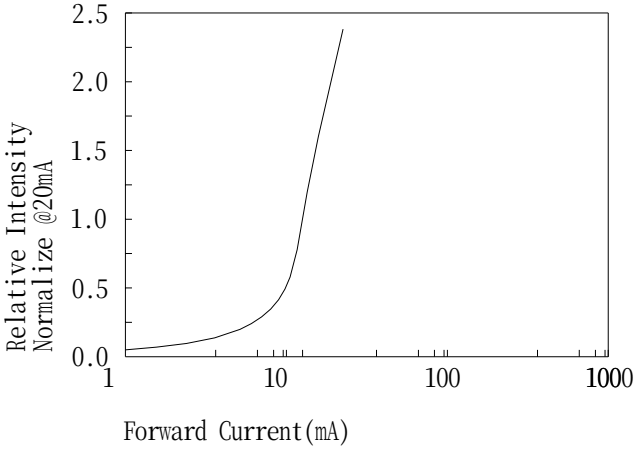


Fig4. Forward Voltage vs. Temperature